

Recitation 1: IC Technology

How are integrated circuits being designed and fabricated?

1. IC Design: application \rightarrow circuits \rightarrow design: design tools include layout, place and route, circuit simulation, etc

2. Fabrication and Integration:

(a) What material that allows the development of microelectronics? a class of materials called “semiconductors”

- two types of “carriers” - electron and hole (the missing of an electron)
- carrier concentrations can be controlled over many orders of magnitude by doping and electric field effects.

Examples of semiconductors: GaAs, GaN, **Si**, Ge. This class will focus on Si.

(b) How to make Si wafers (from sand, crystal growth ...?)

(c) Fabrication

- Defining area: “Lithography” (mostly in industry - **photolithography**)
- Cutting out material = “etching” (wet vs. dry)
- Insulation = SiO_2 (oxide) or Si_3N_4 (nitride), oxidation or nitride deposition
- Tuning conductivity (carrier concentration) = doping (ion implantation)
- Metallic wiring (interconnect): Al now Cu
- Chemical-mechanical polishing (CMP)

(d) The heart of microelectronics

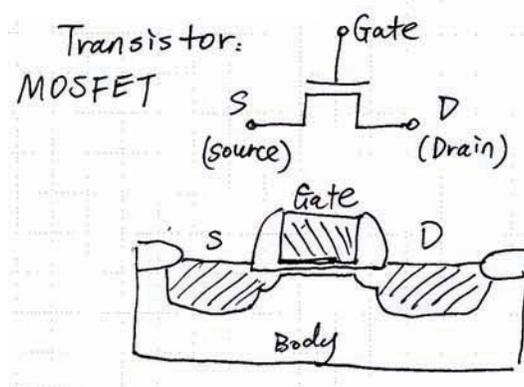


Figure 1: The Transistor

MIT OpenCourseWare
<http://ocw.mit.edu>

6.012 Microelectronic Devices and Circuits
Spring 2009

For information about citing these materials or our Terms of Use, visit: <http://ocw.mit.edu/terms>.